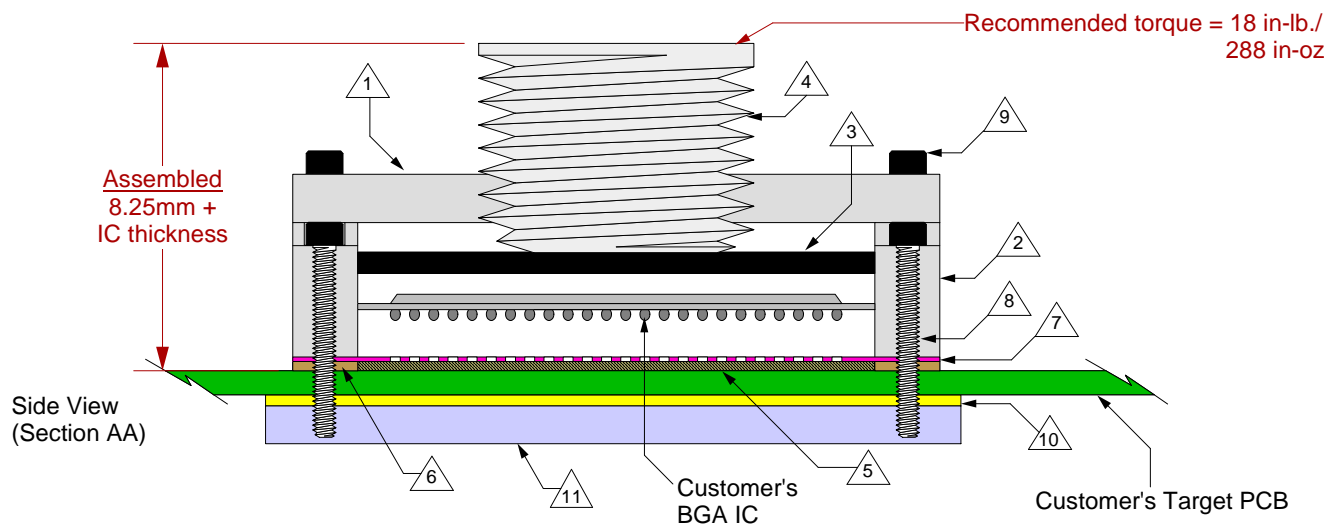
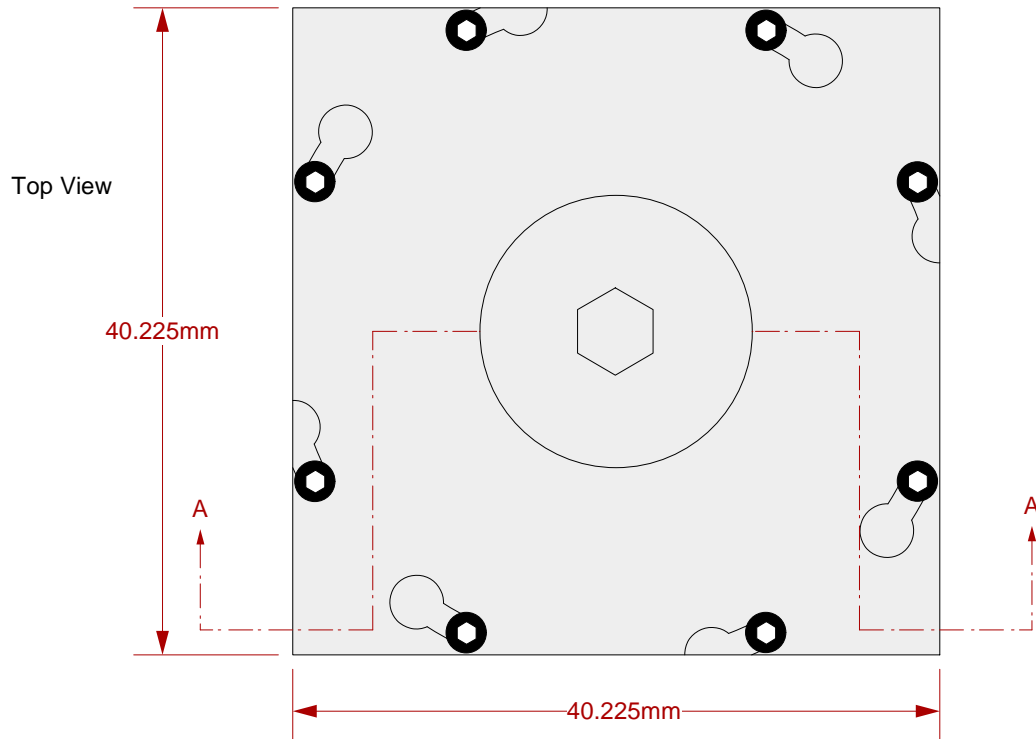



# GHz BGA Socket - Direct mount, solderless

## Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

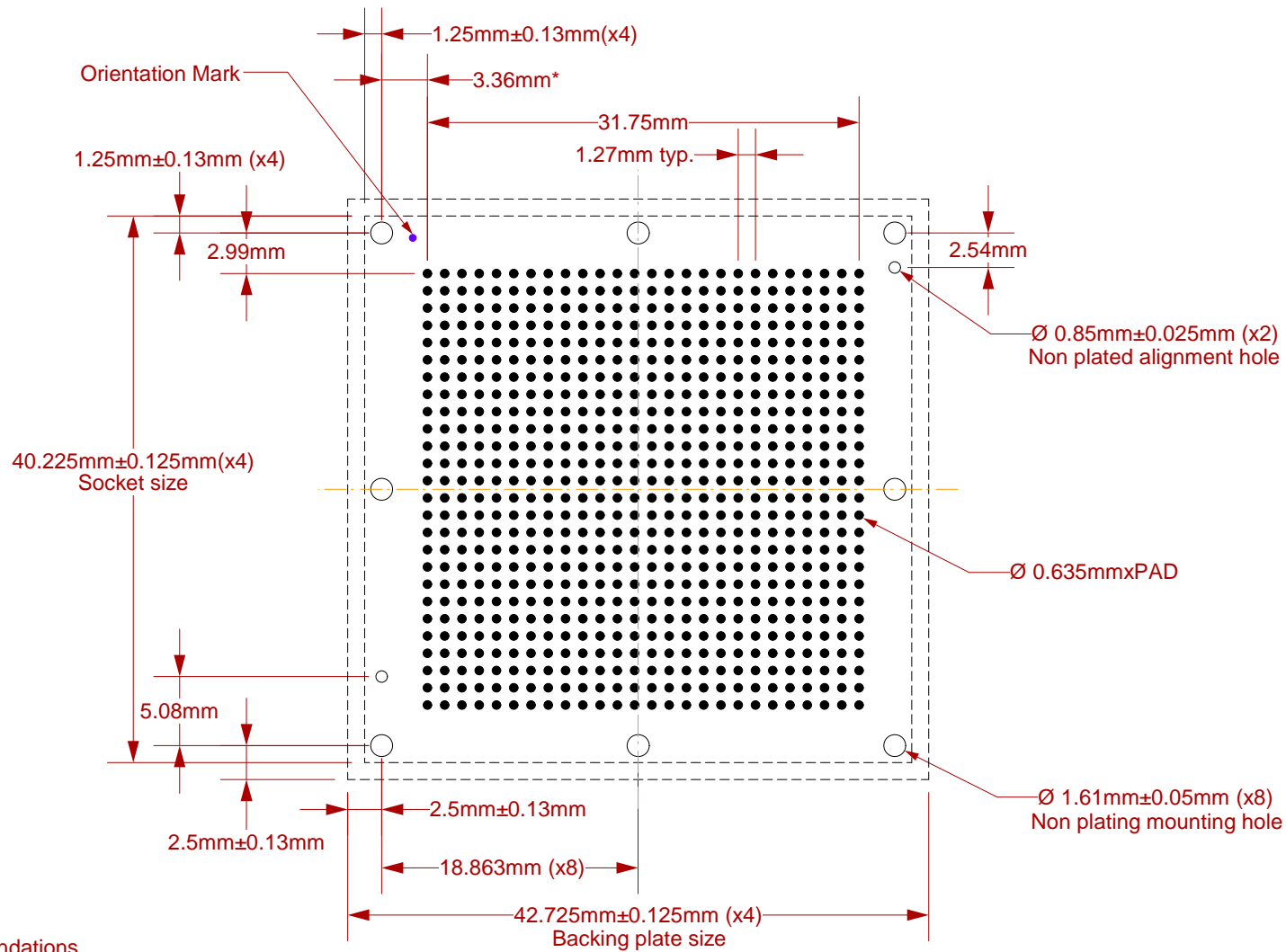


- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △ 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.725mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 12.7mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

	<b>SG-BGA-6194 Drawing</b>	Status: Released	Scale: -	Rev: B
	© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: J. Glab	Date: 10/26/06	
		File: SG-BGA-6194 Dwg.mcd	Modified: 6/15/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

**\*Note: BGA pattern is not symmetrical with respect to the mounting holes.**




Target PCB Recommendations

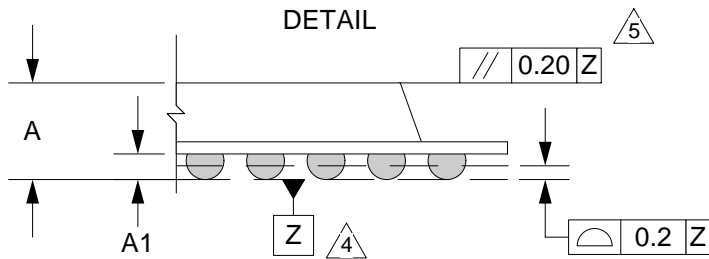
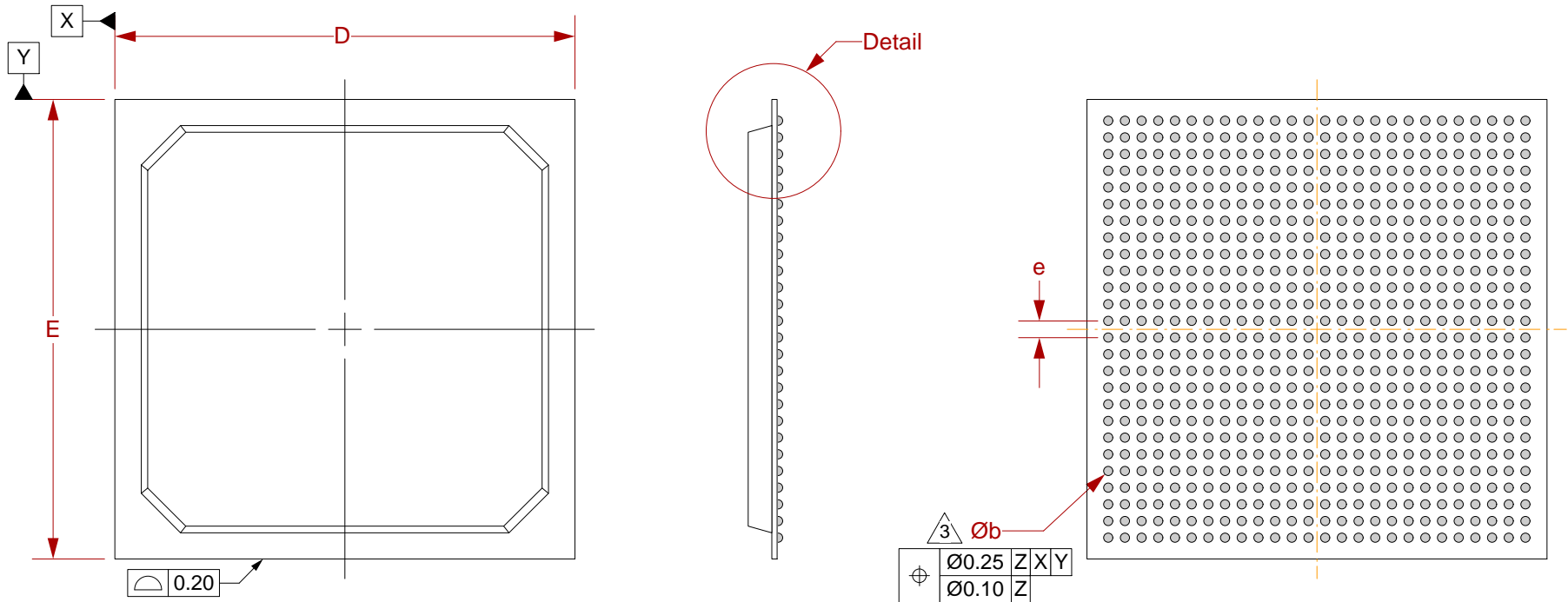
Total thickness: 2.4mm min.  
Plating: Gold or Solder finish  
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.

	<b>SG-BGA-6194 Drawing</b>	Status: Released	Scale: -	Rev: B
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		File: SG-BGA-6194 Dwg.mcd	Modified: 6/15/09, AE	


Compatible BGA Spec



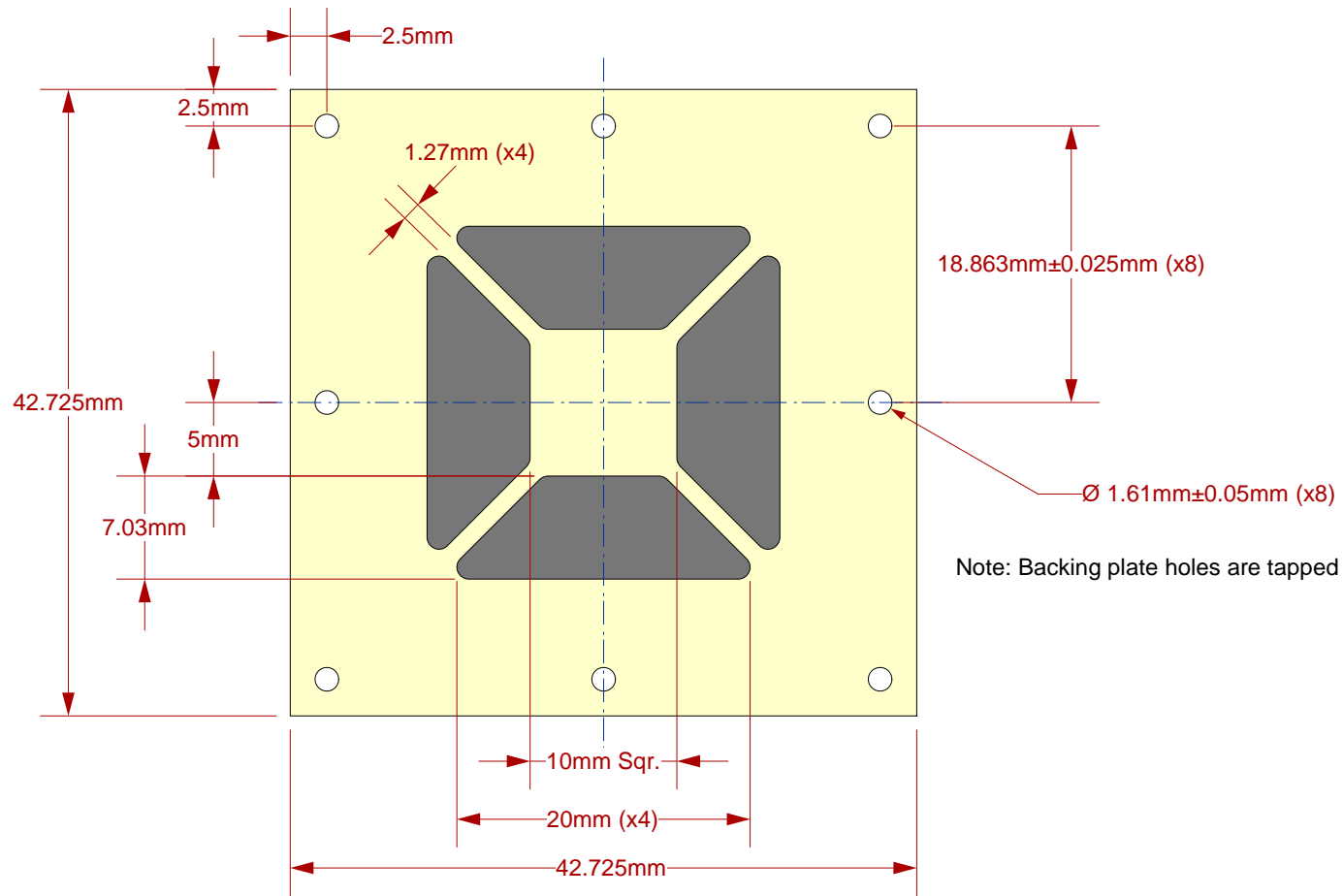
- ① Dimensions are in millimeters.
- ② Interpret dimensions and tolerances per ASME Y14.5M-1994.
- ③ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- ④ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- ⑤ Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.6
A1	0.35	
b	0.60	0.90
D	35.0 BSC	
E	35.0 BSC	
e	1.27 BSC	

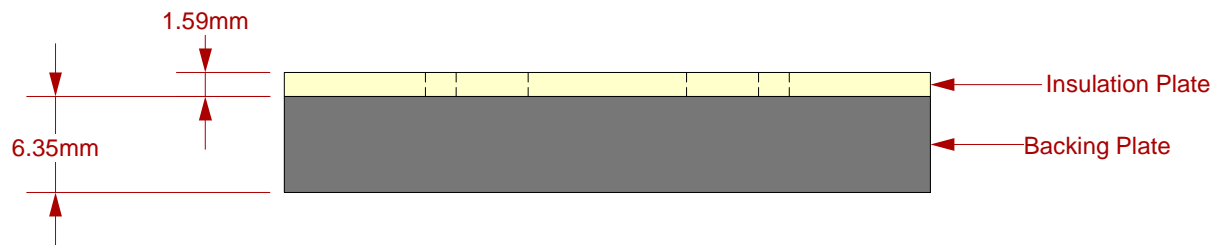
Array 26x26

 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p><b>SG-BGA-6194 Drawing</b></p>	<p>Status: Released</p>	<p>Scale: -</p>	<p>Rev: B</p>
	<p>Drawing: J. Glab</p>	<p>Date: 10/26/06</p>		
	<p>File: SG-BGA-6194 Dwg.mcd</p>	<p>Modified: 6/15/09, AE</p>		

Top View




Side View



Description: Insulation Plate and Backing Plate

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		File: SG-BGA-6194 Dwg.mcd		Modified: 6/15/09, AE

All dimensions are in mm.  
 All tolerances are +/- 0.125mm.  
 (Unless stated otherwise)